

# 20V Dual N-Channel Enhancement-Mode MOSFET

**V<sub>DS</sub>= 20V**

R<sub>DS(ON)</sub>, V<sub>GS</sub>@4.5V, I<sub>DS</sub>@4A = 28 m

R<sub>DS(ON)</sub>, V<sub>GS</sub>@2.5V, I<sub>DS</sub>@2A = 40 m

## Features

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

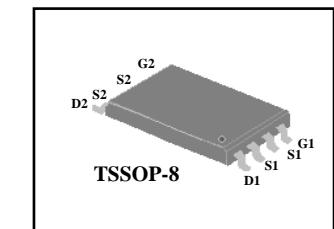
High Power and Current handling capability

Ideal for Li ion battery pack applications

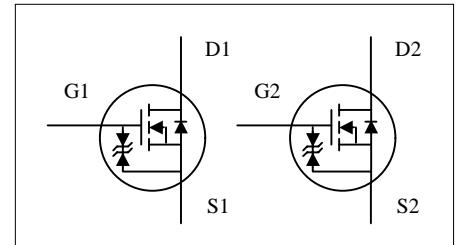
we declare that the material of product

compliance with RoHS requirements.

**LN9926L**



- ▼ Low on-resistance
- ▼ Capable of 2.5V gate drive
- ▼ Low drive current
- ▼ Surface mount package



## Absolute Maximum Ratings

| Symbol                               | Parameter                             | Rating     | Units |
|--------------------------------------|---------------------------------------|------------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage                  | 20         | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage                   | ± 12       | V     |
| I <sub>D</sub> @T <sub>A</sub> =25°C | Continuous Drain Current <sup>3</sup> | 4.6        | A     |
| I <sub>D</sub> @T <sub>A</sub> =70°C | Continuous Drain Current <sup>3</sup> | 3.7        | A     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>1</sup>     | 20         | A     |
| P <sub>D</sub> @T <sub>A</sub> =25°C | Total Power Dissipation               | 1          | W     |
|                                      | Linear Derating Factor                | 0.008      | W/°C  |
| T <sub>STG</sub>                     | Storage Temperature Range             | -55 to 150 | °C    |
| T <sub>J</sub>                       | Operating Junction Temperature Range  | -55 to 150 | °C    |

## Thermal Data

| Symbol             | Parameter  | Value    | Unit |
|--------------------|--|----------|------|
| R <sub>thj-a</sub> | Thermal Resistance Junction-ambient <sup>3</sup> | Max. 125 | °C/W |

**LN9926L**
**Electrical Characteristics@T<sub>j</sub>=25°C(unless otherwise specified)**

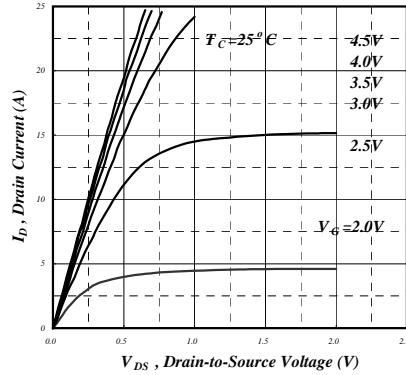
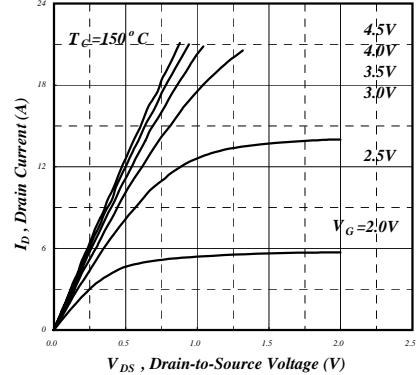
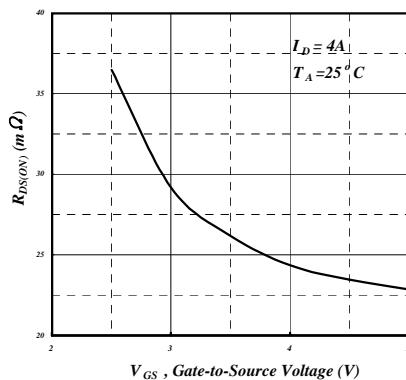
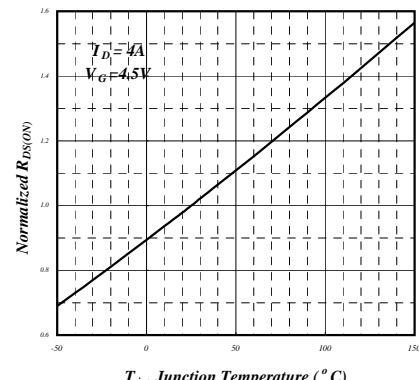
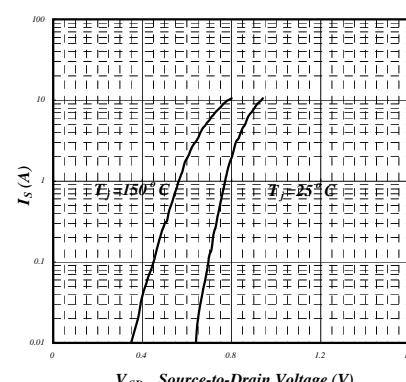
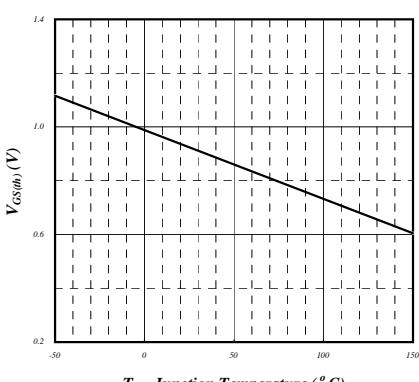
| Symbol                                 | Parameter   | Test Conditions  | Min. | Typ. | Max. | Units |
|--|---|--|------|------|------|-------|
| BV <sub>DSS</sub>                      | Drain-Source Breakdown Voltage                      | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA   | 20   | -    | -    | V     |
| Δ BV <sub>DSS</sub> / Δ T <sub>j</sub> | Breakdown Voltage Temperature Coefficient           | Reference to 25°C, I <sub>D</sub> =1mA   | -    | 0.1  | -    | V/°C  |
| R <sub>DS(ON)</sub>                    | Static Drain-Source On-Resistance <sup>2</sup>      | V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A  | -    | -    | 28   | mΩ    |
|  |   | V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A  | -    | -    | 40   | mΩ    |
| V <sub>GS(th)</sub>                    | Gate Threshold Voltage                              | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA   | 0.5  | -    | -    | V     |
| g <sub>fs</sub>                        | Forward Transconductance                            | V <sub>DS</sub> =10V, I <sub>D</sub> =4.6A   | -    | 9.7  | -    | S     |
| I <sub>DSS</sub>                       | Drain-Source Leakage Current (T <sub>j</sub> =25°C) | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V  | -    | -    | 1    | uA    |
|  | Drain-Source Leakage Current (T <sub>j</sub> =70°C) | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V  | -    | -    | 25   | uA    |
| I <sub>GSS</sub>                       | Gate-Source Leakage                                 | V <sub>GS</sub> =±10 V   | -    | -    | ±10  | uA    |
| Q <sub>g</sub>                         | Total Gate Charge <sup>2</sup>                      | I <sub>D</sub> =4.6A   | -    | 12.5 | -    | nC    |
| Q <sub>gs</sub>                        | Gate-Source Charge                                  | V <sub>DS</sub> =20V   | -    | 1    | -    | nC    |
| Q <sub>gd</sub>                        | Gate-Drain ("Miller") Charge                        |  | -    | 6.5  | -    | nC    |
| t <sub>d(on)</sub>                     | Turn-on Delay Time <sup>2</sup>                     | V <sub>DS</sub> =10V<br>I <sub>D</sub> =1A<br>R <sub>G</sub> =3.3Ω, V <sub>GS</sub> =5V<br>R <sub>D</sub> =10Ω | -    | 5    | -    | ns    |
| t <sub>r</sub>                         | Rise Time   |  | -    | 9    | -    | ns    |
| t <sub>d(off)</sub>                    | Turn-off Delay Time                                 |  | -    | 26.2 | -    | ns    |
| t <sub>f</sub>                         | Fall Time   |  | -    | 6.8  | -    | ns    |
| C <sub>iss</sub>                       | Input Capacitance                                   | V <sub>GS</sub> =0V<br>V <sub>DS</sub> =20V<br>f=1.0MHz  | -    | 355  | -    | pF    |
| C <sub>oss</sub>                       | Output Capacitance                                  |  | -    | 190  | -    | pF    |
| C <sub>rss</sub>                       | Reverse Transfer Capacitance                        |  | -    | 85   | -    | pF    |

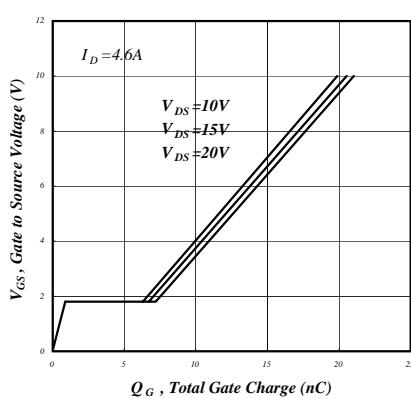
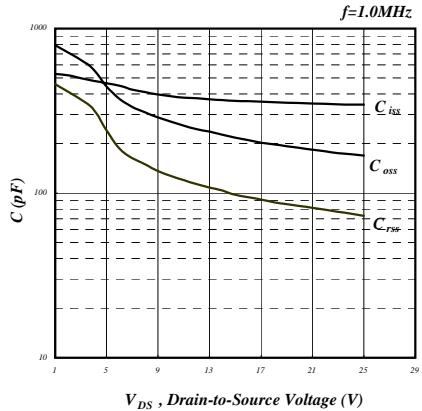
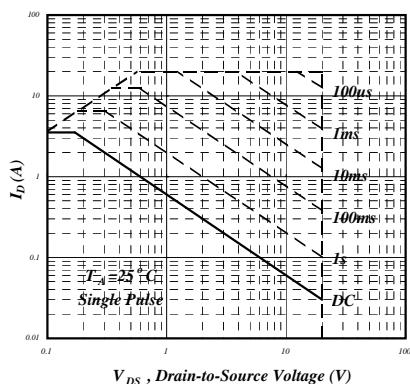
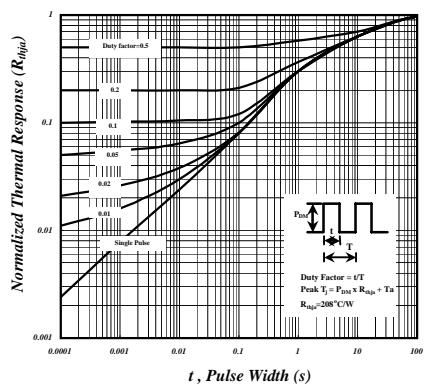
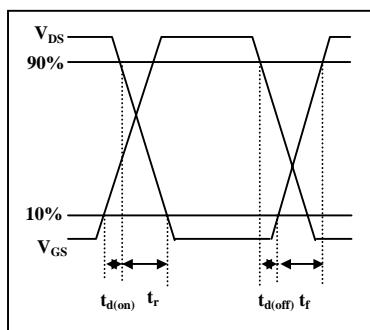
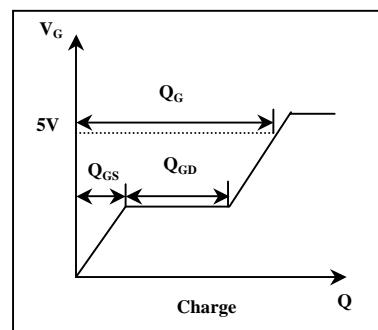
**Source-Drain Diode**

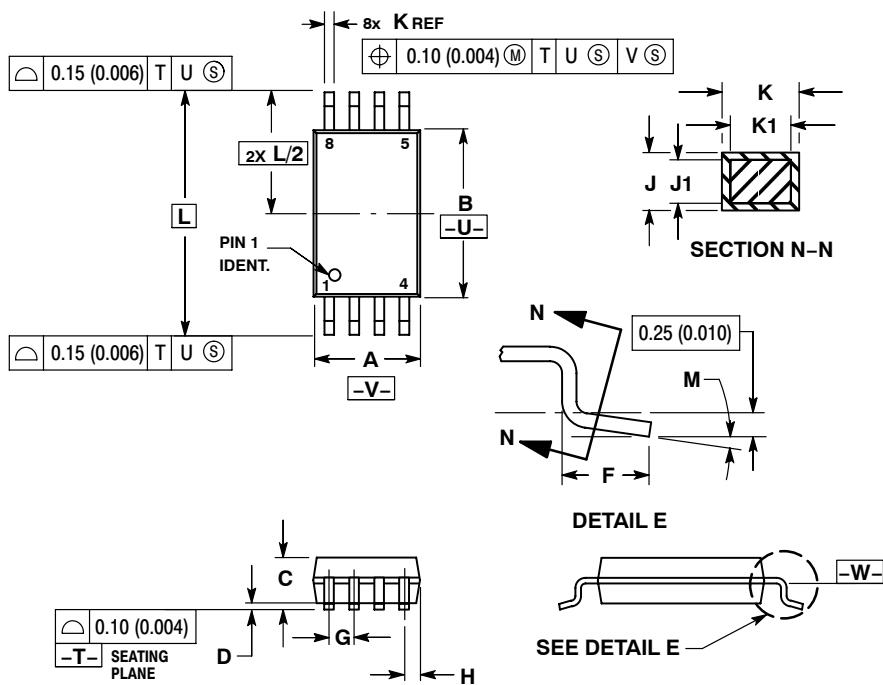
| Symbol          | Parameter                                | Test Conditions  | Min. | Typ. | Max. | Units |
|-----------------|--|--|------|------|------|-------|
| I <sub>S</sub>  | Continuous Source Current ( Body Diode ) | V <sub>D</sub> =V <sub>G</sub> =0V, V <sub>S</sub> =1.2V         | -    | -    | 0.83 | A     |
| V <sub>SD</sub> | Forward On Voltage <sup>2</sup>          | T <sub>j</sub> =25°C, I <sub>S</sub> =1.25A, V <sub>GS</sub> =0V | -    | -    | 1.2  | V     |

**Notes:**

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width  $\leq$ 300us , duty cycle  $\leq$ 2%.
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board ; 208°C/W when mounted on Min. copper pad.

**LN9926L**

**Fig 1. Typical Output Characteristics**

**Fig 2. Typical Output Characteristics**

**Fig 3. On-Resistance v.s. Gate Voltage**

**Fig 4. Normalized On-Resistance**

**Fig 5. Forward Characteristic of Reverse Diode**

**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

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**Fig 7. Gate Charge Characteristics**

**Fig 8. Typical Capacitance Characteristics**

**Fig 9. Maximum Safe Operating Area**

**Fig 10. Effective Transient Thermal Impedance**

**Fig 11. Switching Time Waveform**

**Fig 12. Gate Charge Waveform**

**LN9926L**
**TSSOP-8**

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE  $-W-$ .

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 2.90        | 3.10 | 0.114     | 0.122 |
| B   | 4.30        | 4.50 | 0.169     | 0.177 |
| C   | ---         | 1.20 | ---       | 0.047 |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |
| G   | 0.65 BSC    |      | 0.026 BSC |       |
| H   | 0.50        | 0.60 | 0.020     | 0.024 |
| J   | 0.09        | 0.20 | 0.004     | 0.008 |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |
| L   | 6.40 BSC    |      | 0.252 BSC |       |
| M   | 0°          | 8°   | 0°        | 8°    |